

Spanish detector R&D: strategic areas of expertise for the Higgs factory

CPAN days, Future accelerators network

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CONSEJO SUPERIOR DE INVESTIGACIONES CIENTÍFICAS UNIVERSIDAD DE CANTABRIA

- In this talk, I will simply recall a (non-comprehensive) list of the Spanish groups' areas of expertise.
- Please do not expect updated activities — the time given for preparation was too short..

Scope of the talk:



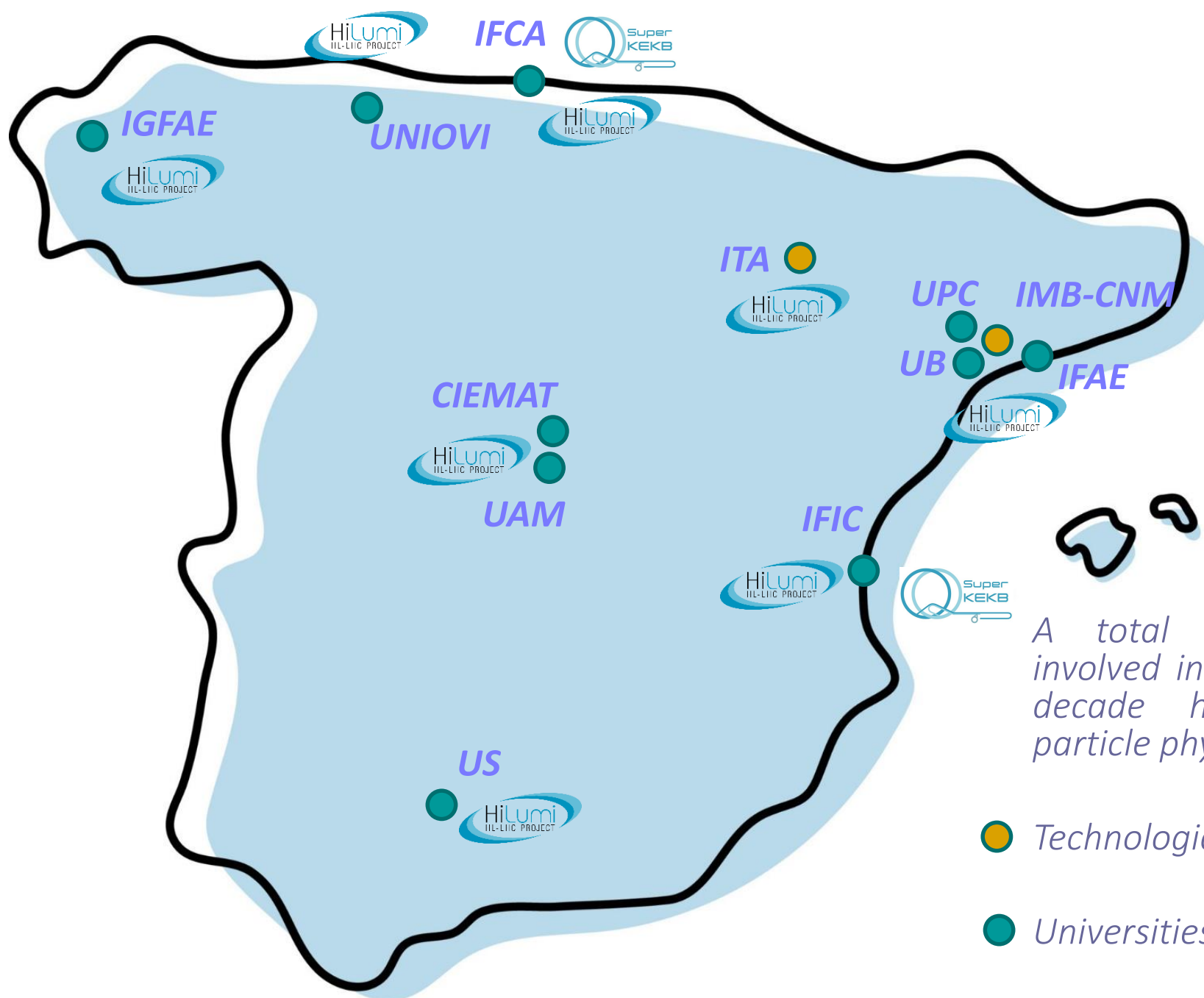
- To provide an overview of the recent activities of the Spanish Particle Physics community in the development of collider experiments, focusing on current R&D efforts for a possible electron-positron collider (Higgs factory).
- To use this as an introduction for a discussion on the role of the Spanish groups in the study of the preferred future experiment by the European Strategy Update?

Outline



- Introduction to the Spanish (known) community.
- Instrumentation R&D activities suitable for FCC-ee experiments, assuming also valid for linear e^+e^- colliders (no really true, but first order correct).
- Discussion

Experiment Builders in Spain



A total of eleven institutions involved in the construction of this decade hadronic and leptonic particle physics colliders

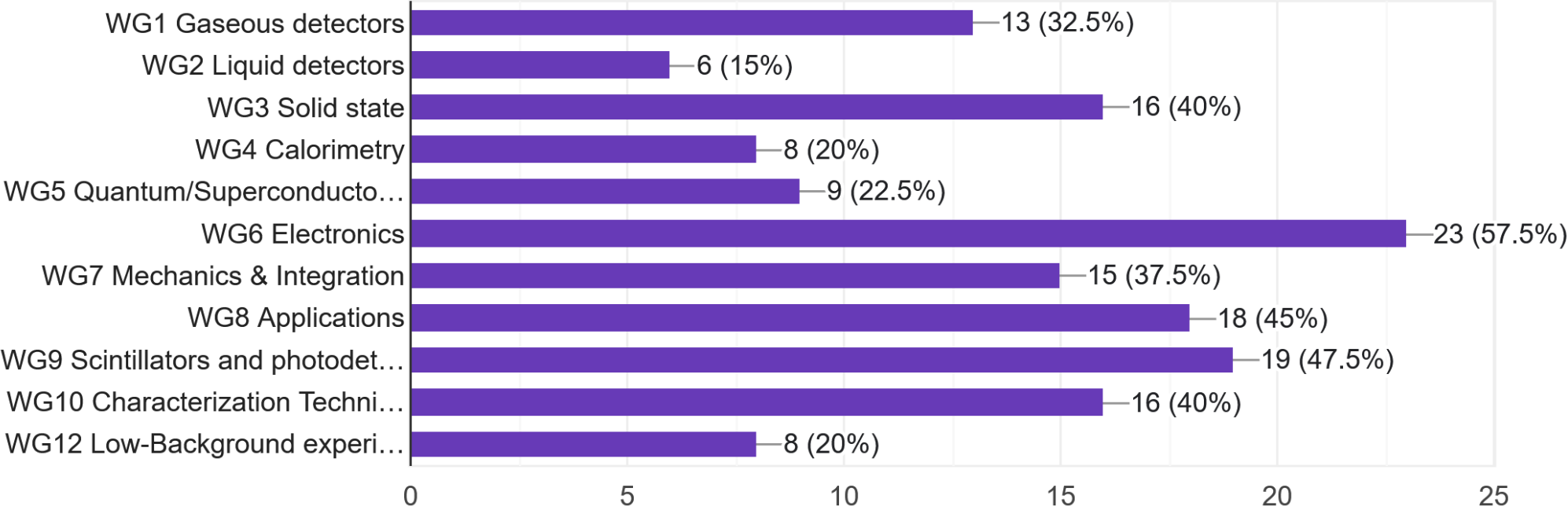
- Technological centers
- Universities and Research Institutes

Is there a strategic area of expertise?



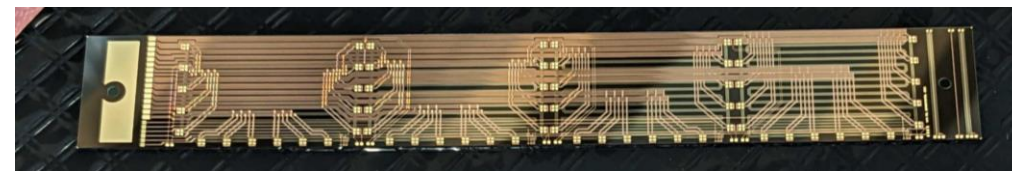
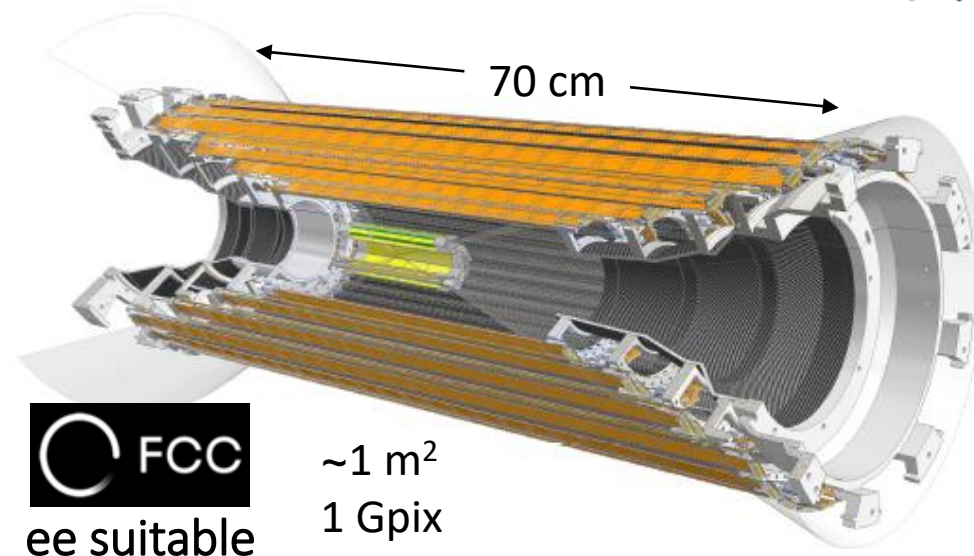
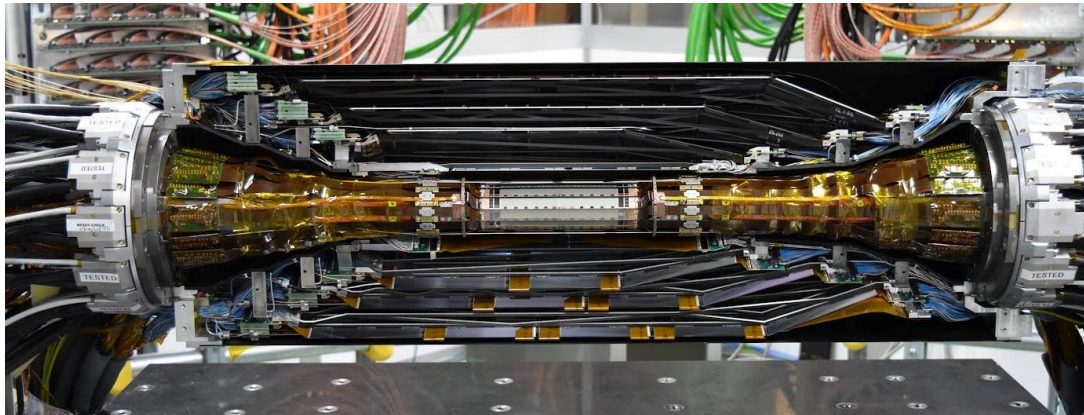
Please select the related CNID Working Groups related with your group activities (select as many as necessary)

40 responses



Vertex detectors - present

High-resolution monolithic pixels: DEPFET & DMAPS



- Belle II PXD (evolving into VTX-CMOS) at KEK
- Belle II technical coordinator, upgrade coordinator, VTX project leader, deputy run manager
- Belle II VTX Upgrade (KEK, Japan):
 - 1 m² Depleted CMOS pixels
- Digital design, wafer postprocessing, characterization, integration

Key sensor specifications:

- Pixel pitch 30-40 μm
- Integration time $\lesssim 100$ ns
- Radiation tolerance: 100 Mrad, 5×10^{14} $n_{\text{eq}}/\text{cm}^2$
- Power dissipation $\lesssim 200$ mW/cm²

Tracking detectors - present

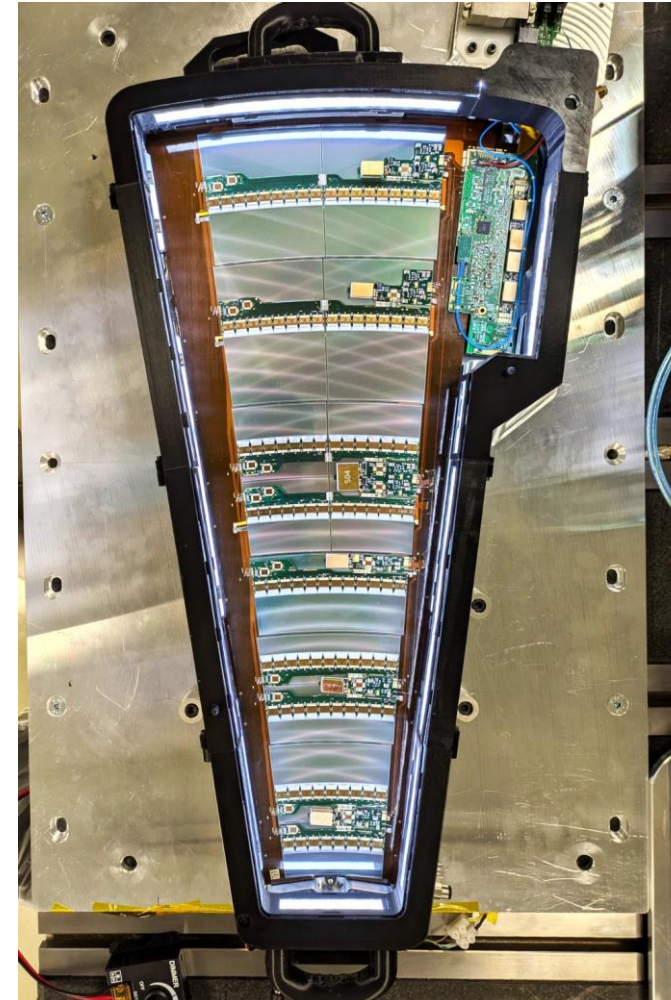
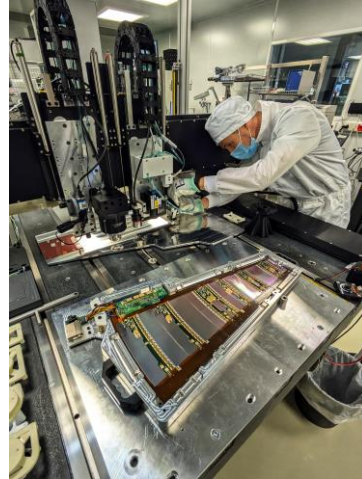
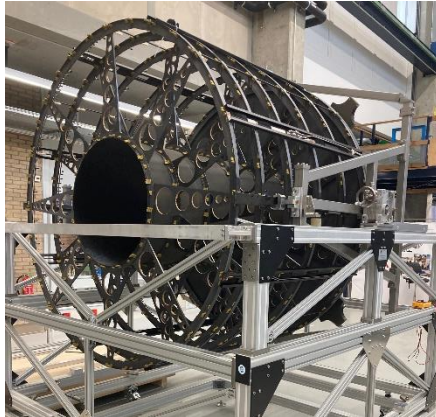
Tracker systems: rad-hard n-in-p strip sensors



hh suitable



ee suitable



- ATLAS ITk: 100 m² Silicon strip sensors
- Involved from early R&D stages all the way down to system development, integration, commissioning and data taking
- Main positions held: ATLAS ITK-Strips deputy project leader, Level 3 coordinators (sensors, integration, production management, services, supports)
- At IFIC Material engineering, interconnections, system integration, module manufacturing, QA/QC.

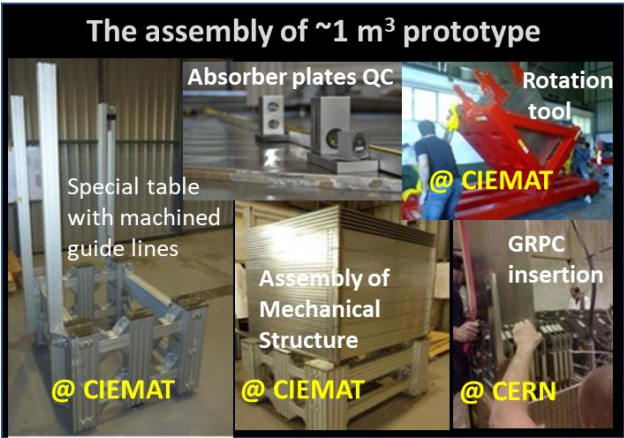


Calorimeters – present

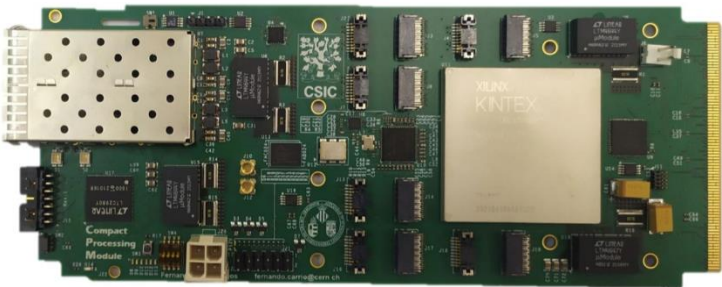
Highly segmented imaging calorimeters.



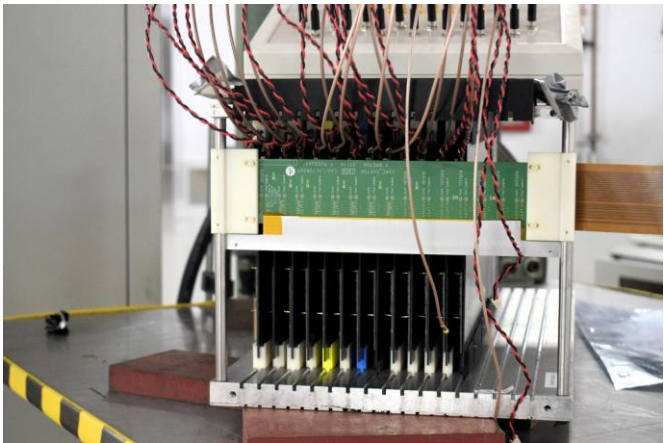
SDHCAL



Hadronic TiCAL



SiW ECAL



- Detector: GRPC, Absorber: Stainless Steel. Embedded electronics: 1x1 cm² pads. Semi-Digital Readout, 2bits - 3 thresholds R&D.
- high precision mechanics (tolerances 50µm, deformations < 500µm)



- 32 PreProcessor boards in ATCA format.
- Interface between on-detector electronics and the trigger and data acquisition system
- Online energy reconstruction of the calorimeter cells at 40 MHz

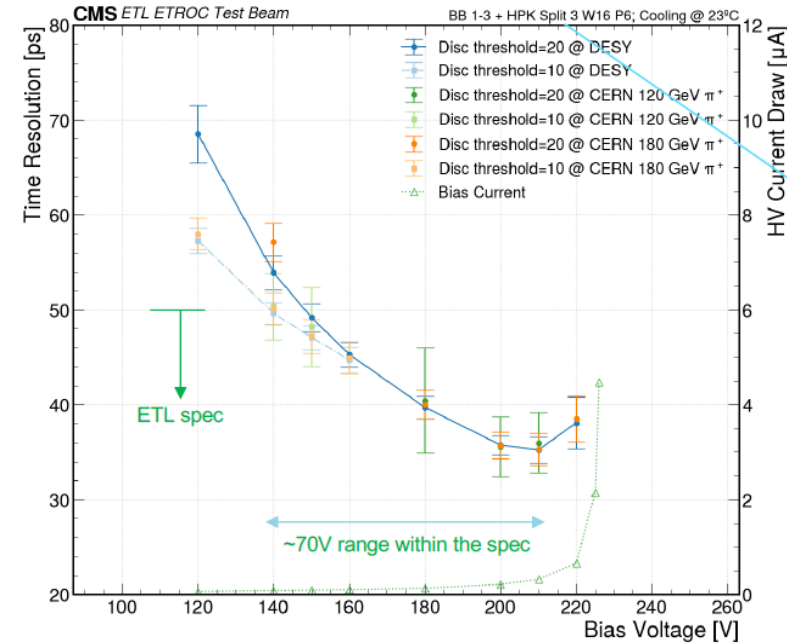
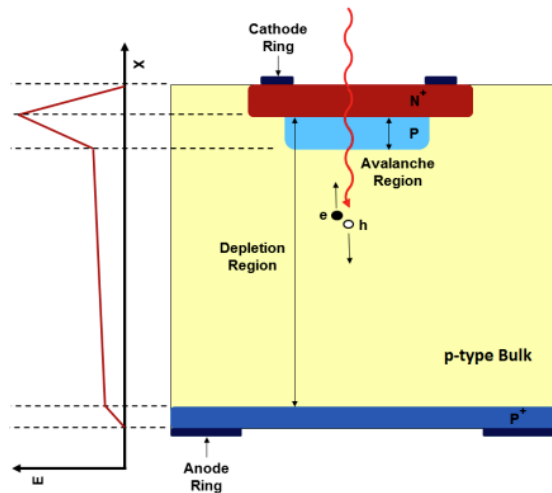


- Sampling calorimeter that uses silicon (Si) as active material and tungsten (W) as absorber material.
- Main role in the commissioning of the SiW-ECAL prototype for beam tests .



Timing detectors - present

Internal Gain : LGAD sensors

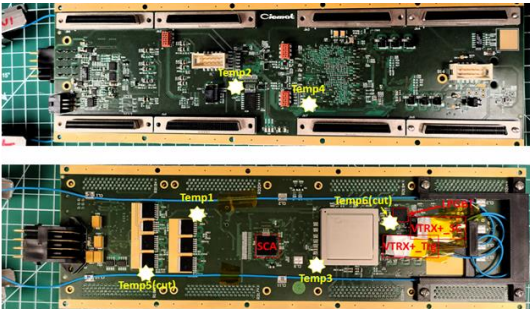
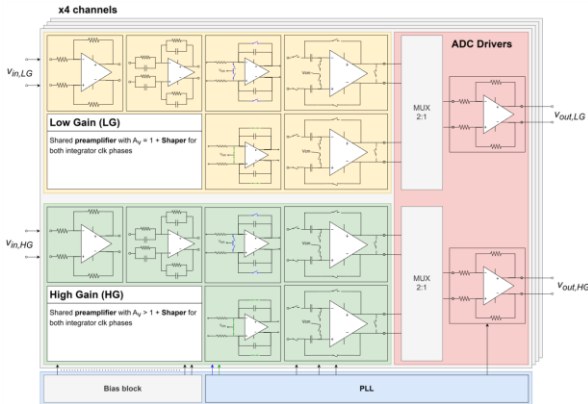


- Contribution to the R&D of LGAD sensors
- Assembly of modules of the HGTD and hybridization.
- Coordination HGTD detector.

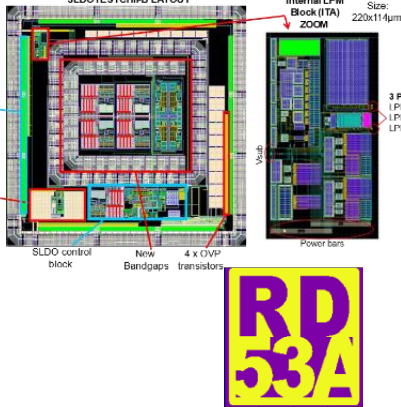
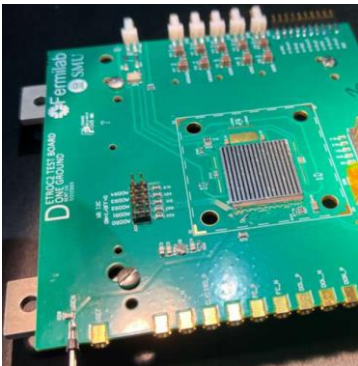
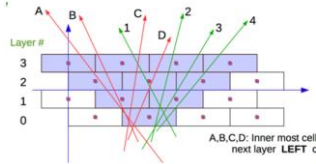


- Contribution to the R&D of LGAD sensors.
- Assembly 900 modules of the Endcap Timing Layer: Automated procedure using SCARA robot, artificial vision for dynamic alignment of components, integrated control of camera, robot arm and vacuum lines
- Coordinators of the Data Performance Group of the MTD : Integration of the MTD in the general CMS tracking

Front-End, Back-End Electronics, DAQ and triggering



OBDTtheta :
DT Frontend TDC&Readout



PicoCal ASIC for LHCb ECAL



- ASIC/chipset in TSMC 65 nm with separate energy and timing processing paths.
- Energy ASIC designed by the UB in collaboration with the UPC and the IFIC.



- DT Frontend TDC & Readout using radiation tolerant flash-based FPGA
- Trigger and Readout back-end on BMTL1 ATCA board Exploring advanced ML / AI based algorithm for muon reconstruction in CMS.



ASIC design & testing - RD53 A/B & CROC for CMS IT (Low power mode circuit, PoR)
Initial Characterization of the ETROC2 ASIC for the ETL timing detector

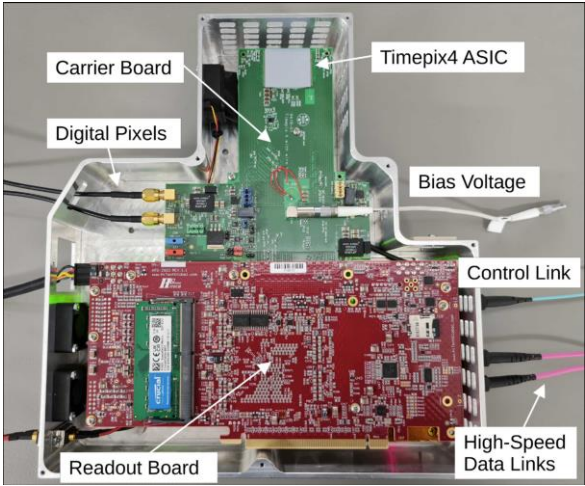
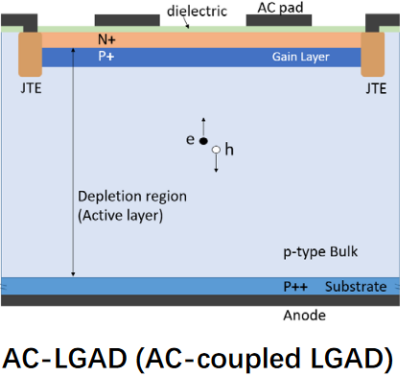
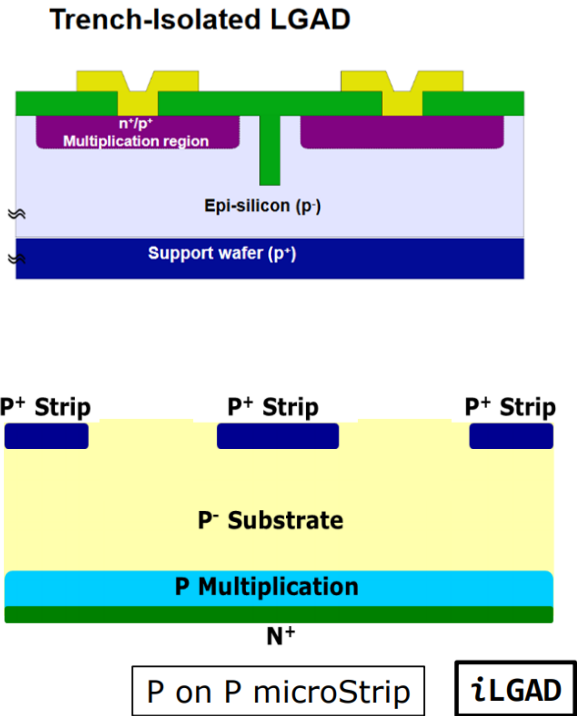
Vertex/Tracking detectors - Strategic R&D

Hybrid sensors for 4D-tracking



- Towards 100% fill factor, small pixel LGADs (many competing options)

- Dedicated project in preparation in WG2 of DRD3



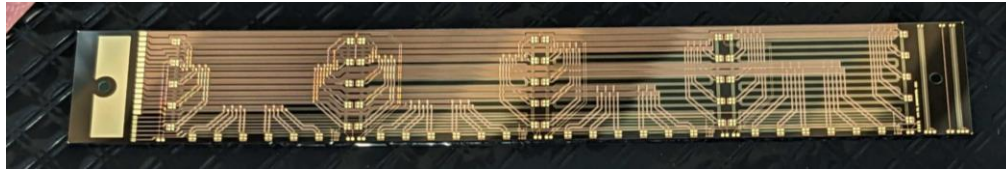
Hybrid design requires ASIC with high-precision time stamping and positon resolution (TIMEPIX4)

Vertex/Tracking detectors - Strategic R&D

Depleted MAPS



Belle II VTX upgrade a stepping stone toward FCCee vertex detector.



High hit efficiency at large hit rate:

Spatial resolution $< 15 \mu\text{m}$

Temporal resolution $< 100 \text{ ns}$

Max. hit rate 120 MHz/cm^2



Material budget:

$0.2\% X_0$ (L1+L2), $0.3\% - 0.8\% X_0$ (L3, L5)

Demonstrator building as part of DRD3 WG2 project

- IFAE working on DMAPS design, fabrication and characterization since 2014

- **CEPC vertex detector** will use monolithic devices, total area $\sim 0.5 \text{ m}^2$, resolution $3\text{-}5 \mu\text{m}$, power 40 mW/cm^2 , low material

- IFAE worked on the design and characterization of the first and second DMAPS prototypes:

- TaichuPix1 and Taichupix2

- Pixel size: $25 \times 25 \mu\text{m}^2$, matrix: 64×192 , hit driven readout

- IFAE plans to continue to work on DMAPS and other novel silicon technologies for future colliders in the context of the DRD3

- IFAE is organizing next CEPC Workshop in Barcelona (May 5th-8th 2025)



Calorimeters - Strategic R&D

5D - Calorimetry

DRD1 & DRD6



ee suitable



hh suitable



Hadronic Calorimeters(DRD1 & DRD6)

- High precision mechanics R&D for real scale calorimeter.
- 5D Calorimeter t-SDHCAL
 - Introducing precise timing (tens of picoseconds) with MultiGap-RPC
- t-SDHCAL for FCCee.
 - Continuous beam, No power-pulsed electronics, higher rates (mainly at Z pole)

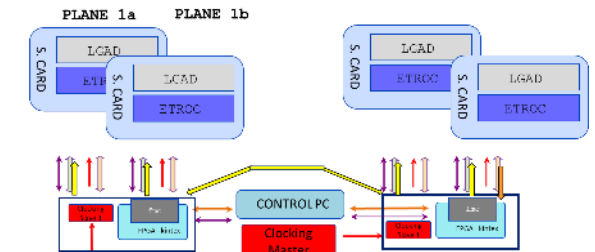


Electromagnetic Calorimeter (DRD6)

- IFIC will become the hub for module hybridization R&D / production / commissioning for DRD6 Si-ECALs and for both ECALs for the LUXE experiment
- Considering LGAD for 5D calorimetry.

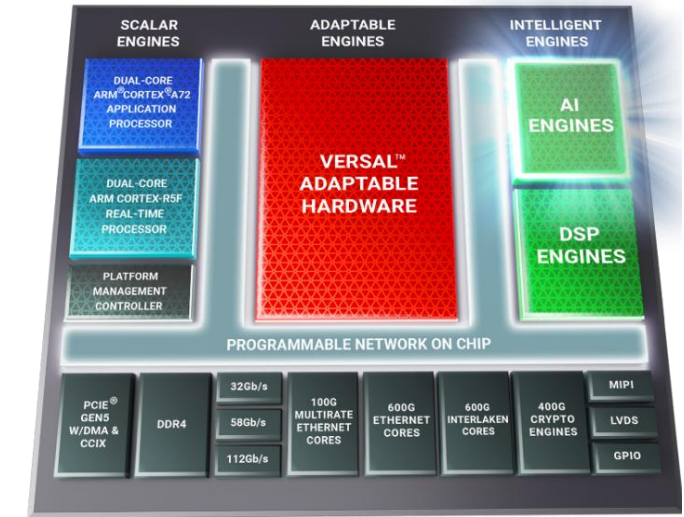
Power and timing

- WG7.1b aims to develop power distribution systems suitable for future particle physics application (ITA)
 - ITA is developing a Radiation-Tolerant GaN based DC-DC Converter for serial powering
- WG7.3b2 aims to study and propose strategies to optimize and assess ultimate precision and determinism of timing distribution systems for future detectors
 - Ciemat: Precise & deterministic timing distribution study with Microsemi FPGA. FCC-ee environment could allow use of Flash-based FPGAs coupled with SEU mitigation techniques in most regions of the detector
 - ITA: evaluate a prototype of a distributed clock network based on White Rabbit Technology to measure the time of flight of particles with accuracies in the sub-nanosecond range.
- DRD7.5a: “TDAQ” in “COTS electronics (Ciemat)

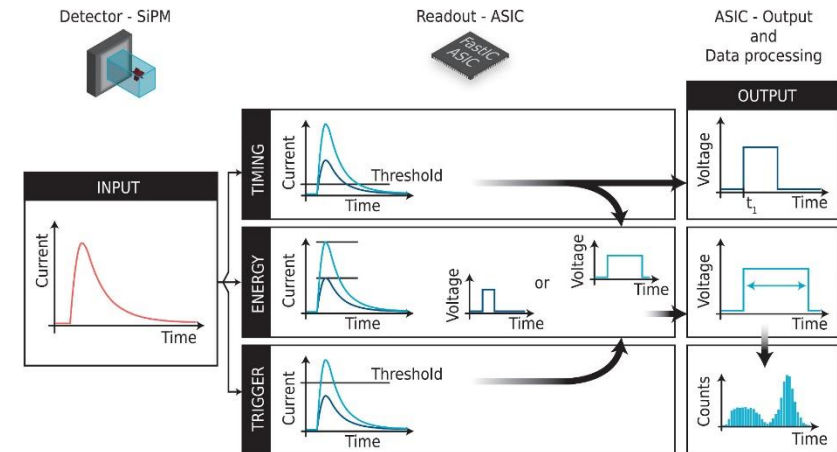


Trigger and ASIC Design

- UNIOVI: Muon trigger (in collaboration with CIEMAT): expand existing low-latency algorithms to detect and trigger on non-standard signatures such as hadronic showers or slow charged particles.
- GNN for real-time ($O(\mu s)$) muon reconstruction, using Versal ACAP and the AI engines.
- Hardware/Setup:
 - Setting up a local test stand for benchmarking firmware.
 - Various devices available for testing: Xilinx Kintex, Virtex Ultrascale+, Versal 7nm AI.



- UB: fast low-noise full readout chain of PMT/MCP/SiPM, targeting single-photon counters inside de DRD4 collaboration in photodectors.
- FastIC ASIC family, currently under development by Barcelona and CERN to read out fast timing detectors with an intrinsic gain of $\sim 10^5$ - 10^6 , such as Silicon PhotoMultipliers, Micro Channel Plates, or Photomultiplier tubes.

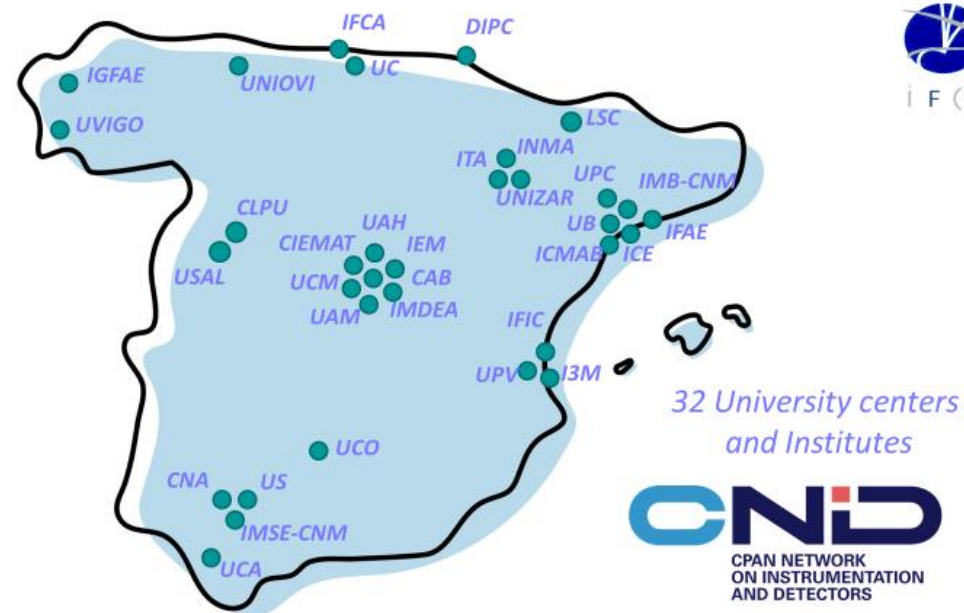


DISCUSSION



IFCA

- Now that the FCC-ee (+hh) appears to be the next flagship priority for the European EPP community, what should our strategy be as detector-building groups?
- How should individual groups articulate their commitments? Should we consolidate activities across groups to improve focus, impact, and visibility—fostering natural synergies without forcing artificial mergers?



RD HEP Roadmap, ivan.vila@csic.es, Benasque, IMFP 2024, September 2024

19